# **Special Issue**

## Microwave/Millimeter-Wave Devices and Metasurfaces

## Message from the Guest Editors

This Special Issue focuses on microwave/millimeterwave devices and metasurfaces, a rapidly evolving field pivotal to 5G/6G communication, intelligent sensing, imaging, and aerospace applications. As emerging technologies demand broadband, miniaturization, and multifunctionality, microwave/millimeter-wave devices (e.g., antennas, filters, and amplifiers) and metasurfaces (with feasible electromagnetic responses) have become core enablers. We aim to showcase cutting-edge research on device design optimization, metasurfacebased wave manipulation, integration technologies, performance validation, and real-world deployments. We warmly invite you to submit original research that advances theoretical foundations, technical innovations, and application prospects in this field. Your insights will enrich academic discourse and drive industrial progress. This Special Issue will showcase high-impact work from global experts, offering a comprehensive view of current trends and future directions. We hope it serves as a valuable platform for knowledge exchange, collaboration, and inspiration.

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### Deadline for manuscript submissions

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#### Editor-in-Chief

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